CLAIMS

What is claimed is:

1. A terminal pin comprising:

an elongated pin for insertion into a hole of a printed circuit board; and

a flange having a shoulder to abut the printed circuit board into which the pin is inserted, the flange being chamfered to provide a vent to the hole of the printed circuit board.

2. A terminal pin as claimed in claim 1 comprising two opposed chamfers.

3. A terminal pin as claimed in claim 2 wherein edges of the two opposed chamfers are at about the periphery of the pin.

4. A circuit module comprising:

a circuit substrate having circuitry thereon; and

at least one rigid terminal pin attached to the circuit substrate, the terminal pin including a flange having a shoulder to abut a printed circuit board into which the pin is inserted, the flange being chamfered to provide a vent to a hole of the printed circuit board into which the pin is inserted.

5. A module as claimed in claim 4 comprising two opposed chamfers.

6. A module as claimed in claim 5 wherein edges of the two opposed chamfers are at about the periphery of the pin.

7. A module as claimed in claim 4 wherein the pin is electrically connected to the circuitry.

8. A circuit board assembly comprising:

a printed circuit board;

a circuit module having circuitry thereon; and

at least one rigid terminal pin attached to the circuit module, the terminal pin including a flange having a shoulder to abut the printed circuit board, the flange being chamfered to provide a vent to a hole of the printed circuit board into which the pin is inserted.

9. A circuit board assembly as claimed in claim 8 comprising two opposed chamfers.

10. A circuit board assembly as claimed in claim 9 wherein edges of the two opposed chamfers are at about the periphery of the pin.

11. A circuit board assembly as claimed in claim 8 wherein the pin is electrically connected to the circuitry.

12. A method of soldering a circuit module to a printed circuit board comprising:

providing at least one rigid terminal pin on the circuit module, the terminal pin including a flange having a shoulder to abut a hole in a printed circuit board into which the pin is inserted, the flange having a chamfer facing the printed circuit board;

positioning the module on the printed circuit board with the pin inserted into a hole in the printed circuit board and the flange shoulder abutting the printed circuit board, the chamfer providing a vent to the hole; and

causing solder to flow through an opening between the chamfer and printed circuit board.

13. A method as claimed in claim 12 wherein the solder is applied in a wave soldering process.

14. A method as claimed in claim 12 wherein the solder is applied in a reflow soldering process.

15. A method as claimed in claim 12 comprising two opposed chamfers.

16. A method as claimed in claim 15 wherein edges of the two opposed chamfers are at about the periphery of the pin.